UNIKC Semiconductor

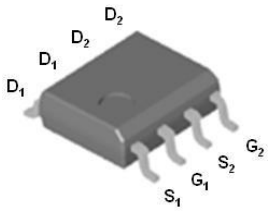
RoHS Compliant

PZ2103NV

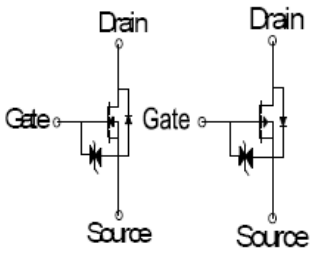
N&P-Channel Enhancement Mode MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D	Channel
30V	21mΩ @V_{GS} = 10V	8A	N
-30V	34mΩ @V_{GS} = -10V	-6A	P



SOP- 08



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	CH.	LIMITS	UNITS
Drain-Source Voltage		V_{DS}	N	30	V
			P	-30	
Gate-Source Voltage		V_{GS}	N	±20	
			P	±20	
Continuous Drain Current	T_A = 25 °C	I_D	N	8	A
			P	-6	
	T_A = 70 °C		N	6	
			P	-5	
Pulsed Drain Current[1]		I_{DM}	N	36	
			P	-27	
Avalanche Current		I_{AS}	N	20	
			P	-20	
Avalanche Energy	L = 0.1mH	E_{AS}	N	21	mJ
			P	21	
Power Dissipation	T_A = 25 °C	P_D	N	2	W
			P	2	
	T_A = 70 °C		N	1.3	
			P	1.3	
Junction & Storage Temperature Range		T_J, T_{STG}		-55 to 150	°C
Lead Temperature ($^1/_{16}$" from case for 10 sec .)		T_L		275	

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THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		40	°C / W
Junction-to-Ambient	$R_{\theta JA}$		62.5	

[1]Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS (T_J = 25 °C, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS		LIMITS MIN	LIMITS TYP	LIMITS MAX	UNIT
STATIC							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	N	30			V
		V_{GS} = 0V, I_D = -250μA	P	-30			
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	N	1.0	1.5	3.0	
		V_{DS} = V_{GS}, I_D = -250μA	P	-1.0	-1.5	-3.0	
Gate-Body Leakage	I_{GSS}	V_{DS} = 0V, V_{GS} = ±16V	N			±25	μA
		V_{DS} = 0V, V_{GS} = ±16V	P			±25	
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 24V, V_{GS} = 0V	N			1	μA
		V_{DS} = -24V, V_{GS} = 0V	P			-1	
		V_{DS} = 20V, V_{GS} = 0V, T_J = 55 °C	N			10	
		V_{DS} = -20V, V_{GS} = 0V, T_J = 55 °C	P			-10	
On-State Drain Current[1]	$I_{D(ON)}$	V_{DS} = 5V, V_{GS} = 10V	N	36			A
		V_{DS} = -5V, V_{GS} = -10V	P	-27			
Drain-Source On-State Resistance[1]	$R_{DS(ON)}$	V_{GS} = 4.5V, I_D = 6A	N		22	31	mΩ
		V_{GS} = -4.5V, I_D = -5A	P		35	56	
		V_{GS} = 10V, I_D = 7A	N		16	21	
		V_{GS} = -10V, I_D = -6A	P		21	34	
Forward Transconductance[1]	g_{fs}	V_{DS} = 10V, I_D = 5A	N		14		S
		V_{DS} = -10V, I_D = -5A	P		8		

DYNAMIC							
Input Capacitance	C_{iss}	N-Channel V_{GS} = 0V, V_{DS} = 15V, f = 1MHz	N		520		pF
			P		1060		
Output Capacitance	C_{oss}		N		159		
		P-Channel V_{GS} = 0V, V_{DS} = -15V, f = 1MHz	P		231		
Reverse Transfer Capacitance	C_{rss}		N		85		
			P		163		

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DYNAMIC							
Total Gate Charge[2]	Q_g	N-Channel V_{DS} = 0.5$V_{(BR)DSS}$, V_{GS} = 10V, I_D = 7A P-Channel V_{DS} = 0.5$V_{(BR)DSS}$, V_{GS} = -10V, I_D = -6A	N		11		nC
			P		19		
Gate-Source Charge[2]	Q_{gs}		N		2		
			P		4		
Gate-Drain Charge[2]	Q_{gd}		N		2.5		
			P		3		
Turn-On Delay Time[2]	$t_{d(on)}$	N-Channel V_{DS} = 15V $I_D \cong$ 1A, V_{GS} = 10V, R_{GEN} = 6Ω P-Channel V_{DS} = -15V, R_L = 1Ω $I_D \cong$ -1A, V_{GS} = -10V, R_{GEN} = 6Ω	N		9		nS
			P		10		
Rise Time[2]	t_r		N		11		
			P		15		
Turn-Off Delay Time[2]	$t_{d(off)}$		N		18		
			P		68		
Fall Time[2]	t_f		N		20		
			P		34		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T_A = 25 °C)							
Continuous Current	I_S		N			8	A
			P			-6	
Forward Voltage[1]	V_{SD}	I_F = 7A, V_{GS} = 0V I_F = -6A, V_{GS} = 0V	N			1	V
			P			-1	
Reverse Recovery Time	t_{rr}	I_F = 7A, dI_F/dt = 100A / μS I_F = -6A, dI_F/dt = 100A / μS	N		15.5		nS
			P		15.5		
Reverse Recovery Charge	Q_{rr}		N		7.9		nC
			P		7.9		

[1]Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

[2]Independent of operating temperature.

Remark： ESD protected Gate.

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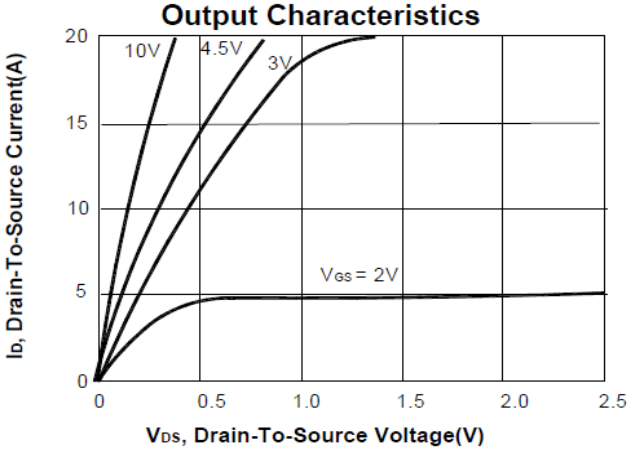
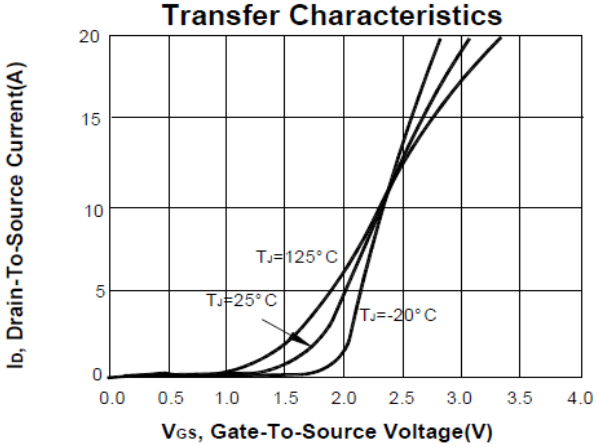
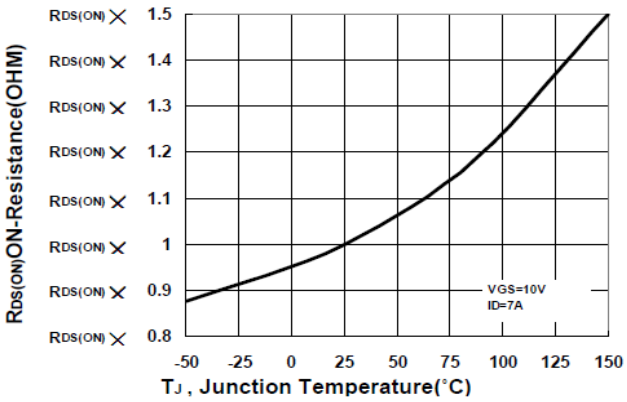
Output Characteristics



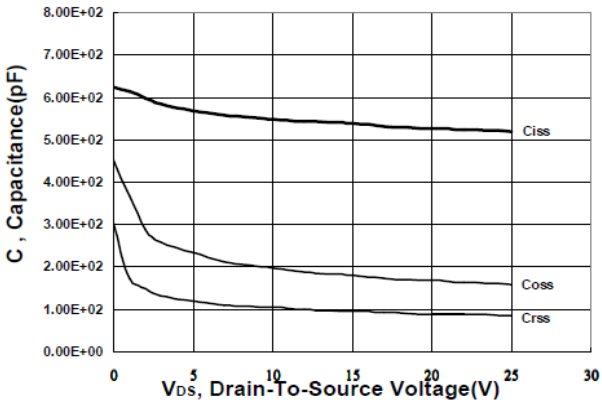
Transfer Characteristics



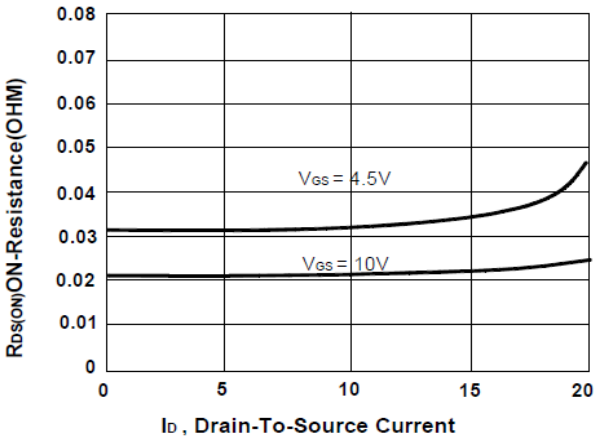
On-Resistance VS Temperature



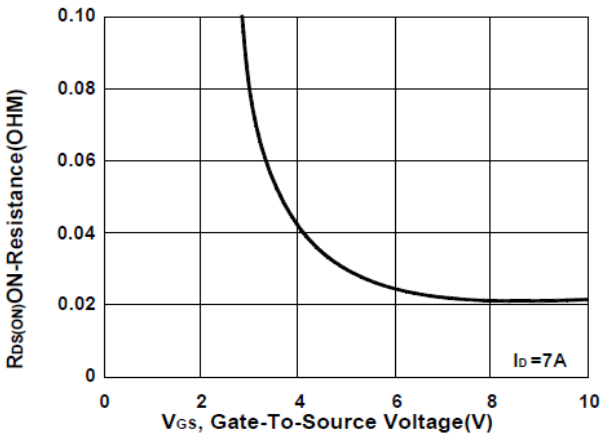
Capacitance Characteristic



On-Resistance VS Drain Current



On-Resistance VS Gate-To-Source



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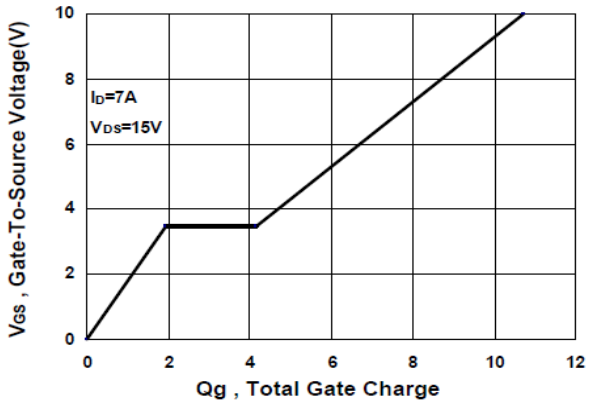
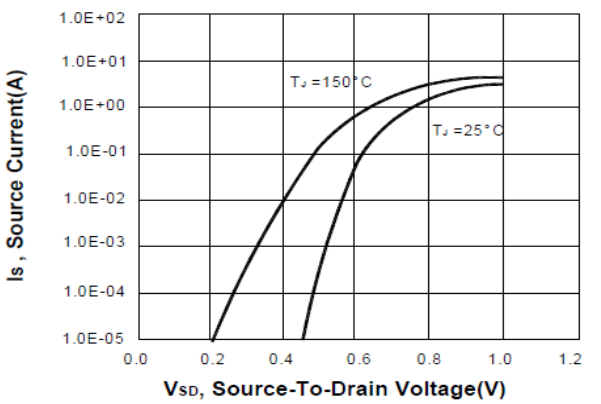
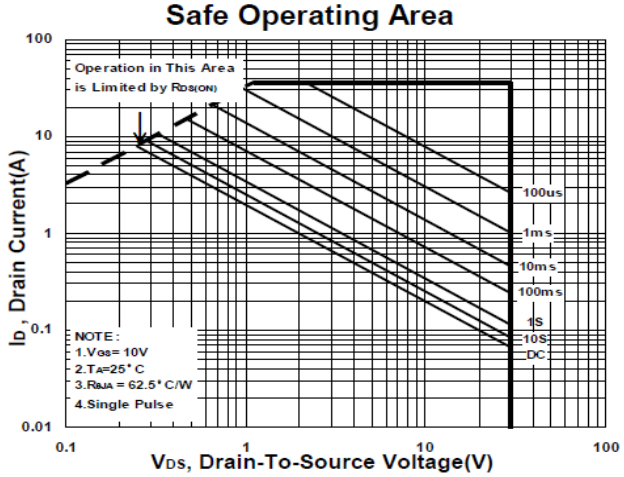
Gate charge Characteristics



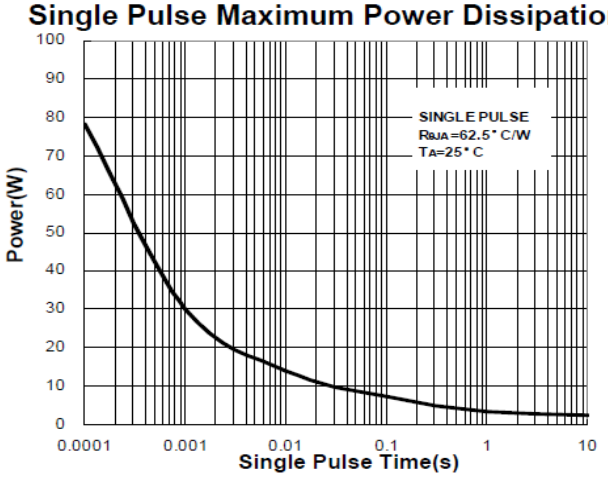
Source-Drain Diode Forward Voltage



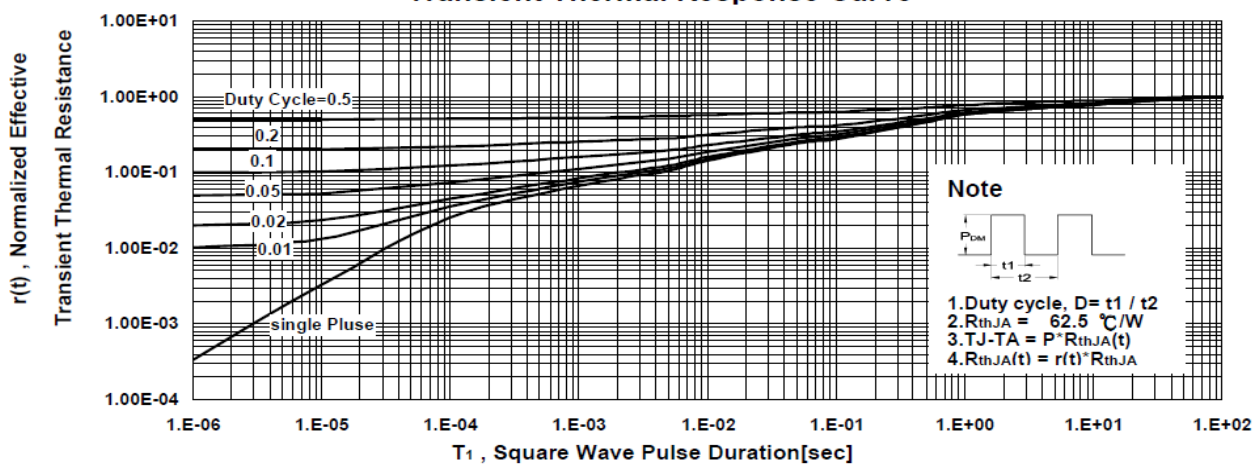
Safe Operating Area



Single Pulse Maximum Power Dissipation



Transient Thermal Response Curve



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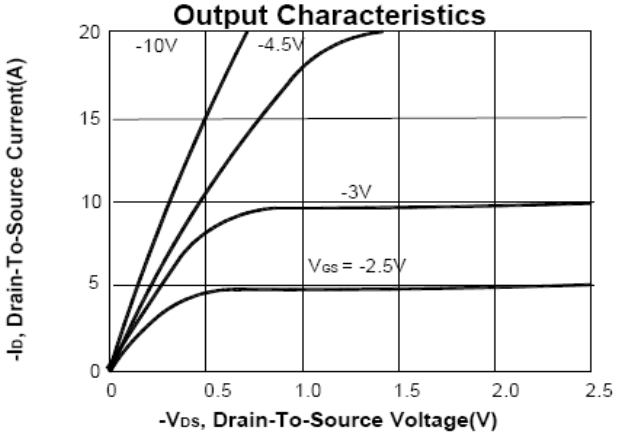
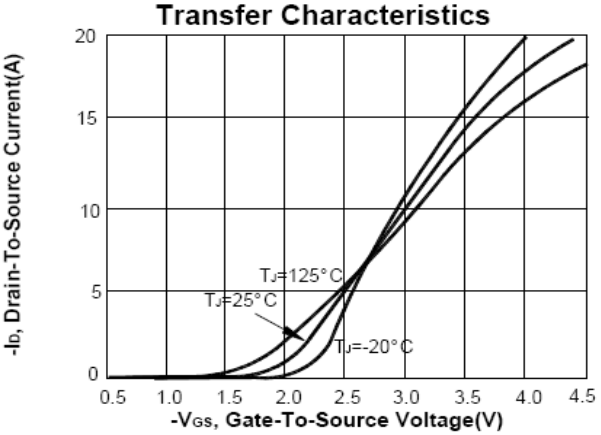
TYPICAL PERFORMANCE CHARACTERISTICS
P-CHANNEL

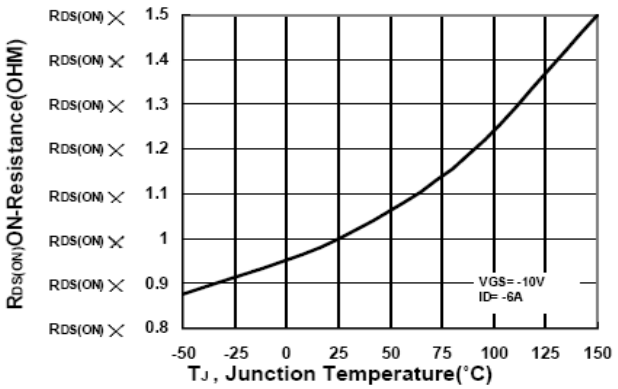
Output Characteristics



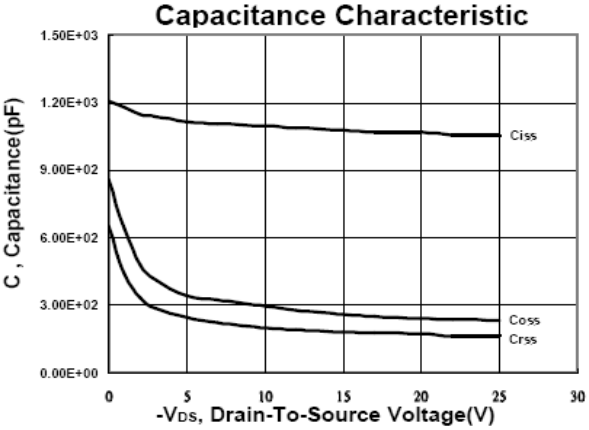
Transfer Characteristics



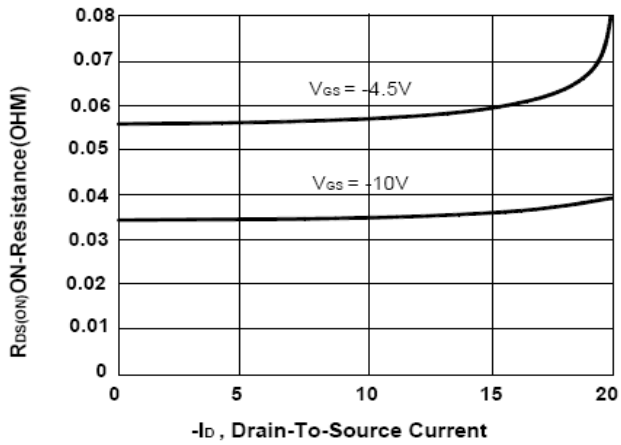
On-Resistance VS Temperature



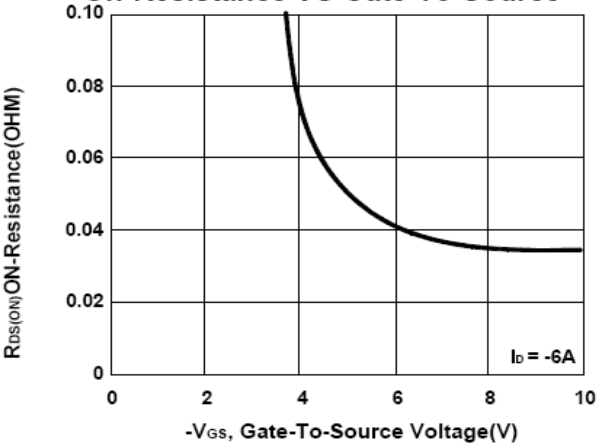
Capacitance Characteristic



On-Resistance VS Drain Current



On-Resistance VS Gate-To-Source



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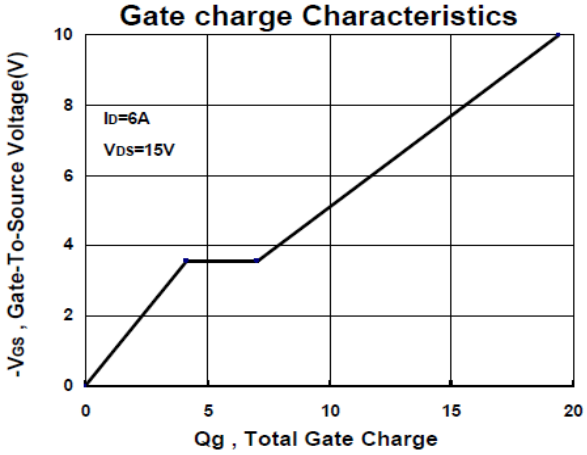

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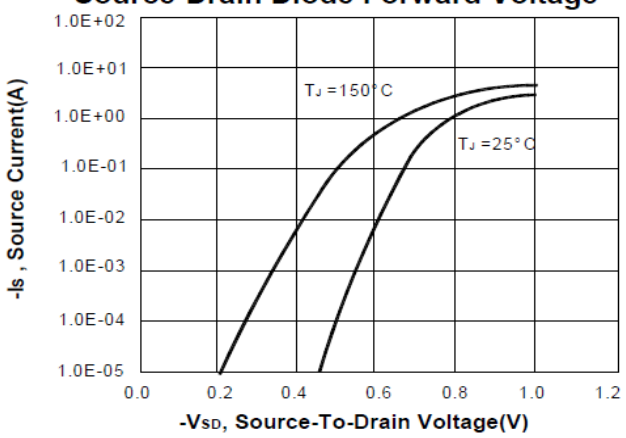
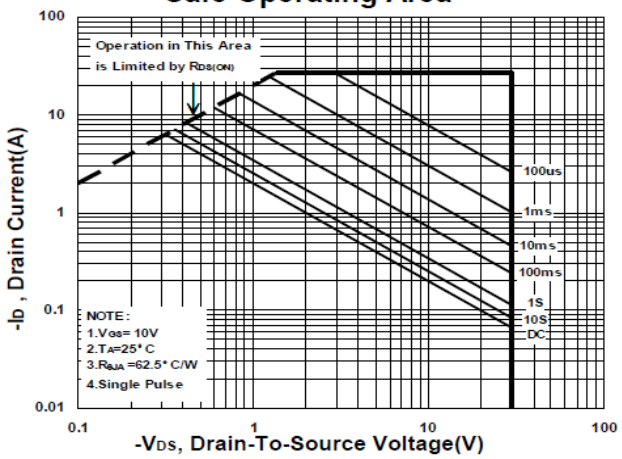


Safe Operating Area



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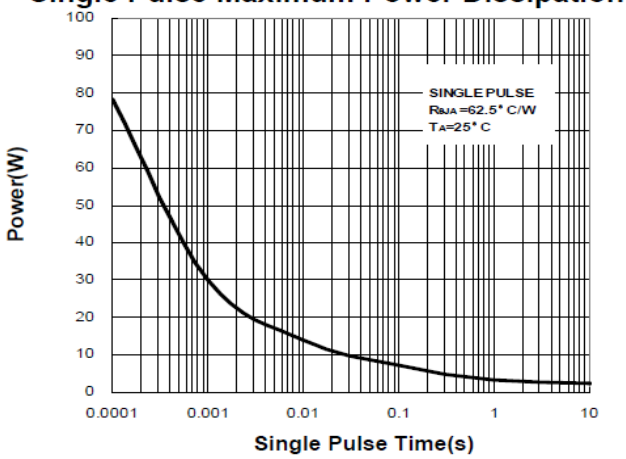

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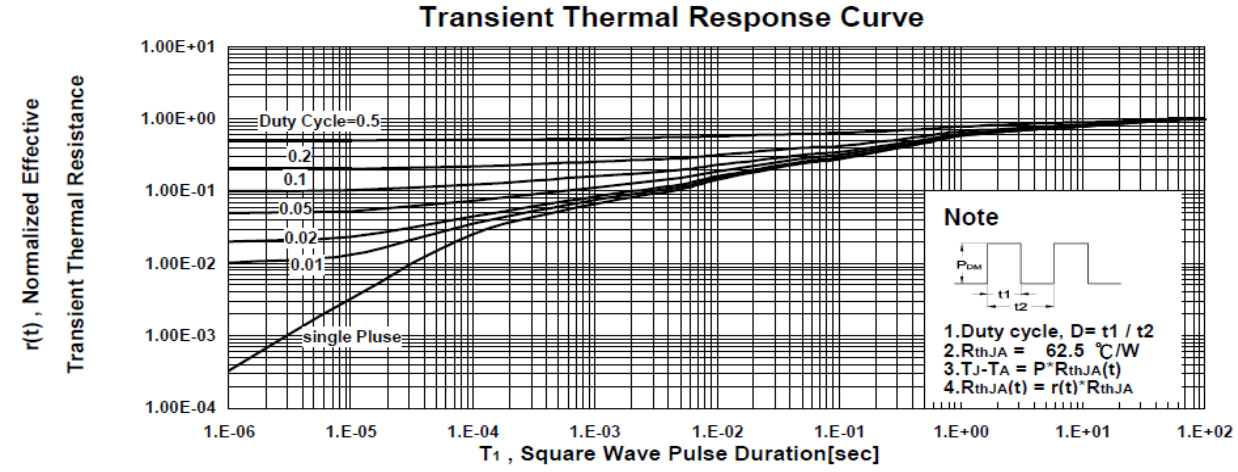

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Package Dimension

SOP-8 MECHANICAL DATA

Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25